

XDFN4 0.8x0.8, 0.48P CASE 711AB-01 **ISSUE O**

DATE 21 OCT 2010

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION b APPLIES TO PLATED TERMINALS.
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS		
DIM	MIN	MAX	
Α		0.40	
A1	0.00	0.05	
А3	0.10 REF		
b	0.17	0.27	
D	0.80 BSC		
D2	0.20	0.30	
Е	0.80 BSC		
е	0.48 BSC		
L	0.23	0.33	
L2	0.17	0.27	
13	0.01	0.11	

GENERIC MARKING DIAGRAM*

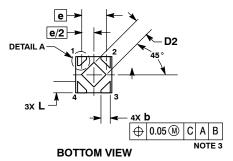


= Specific Device Code Χ

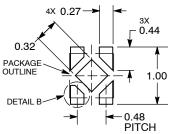
MM = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

4X L3 **•D**→ PIN ONE REFERENCE 0.06 0.05 **DETAIL A** 2X | 🗆 | 0.05 | C **TOP VIEW** - 4X 0.17 0.05 C □ 0.05 C C SEATING PLANE NOTE 4 **DETAIL B** SIDE VIEW



RECOMMENDED MOUNTING FOOTPRINT*



DIMENSIONS: MILLIMETERS

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DESCRIPTION:	XDFN4, 0.8X0.8, 0.48P	PAGE 1 OF 2	

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



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